

Rectifier Diodes

SKN 4000
SKN 6000



V_{RSM} V_{RRM} V	I_{FAV} (sin. 180; $T_{case} = \dots$)	
	4000 A (50 °C)	6000 A (85 °C)
200	SKN 4000/02	SKN 6000/02
400	SKN 4000/04	SKN 6000/04
600	SKN 4000/06	SKN 6000/06

Symbol	Conditions	SKN 4000	SKN 6000
I_{FAV}	sin. 180; $T_{case} = 50\text{ °C}; DSC^{1)}$ $= 85\text{ °C}; DSC^{1)}$ $= 100\text{ °C}; DSC^{1)}$	4000 A 3200 A 2740 A	6000 A 5400 A
I_{FSM}	$T_{vj} = 25\text{ °C}; 10\text{ ms}$ $T_{vj} = 180\text{ °C}; 10\text{ ms}$	60 kA 50 kA	
i^2t	$T_{vj} = 25\text{ °C}; 8,3 \dots 10\text{ ms}$ $T_{vj} = 180\text{ °C}; 8,3 \dots 10\text{ ms}$	18000 kA ² s 12500 kA ² s	
I_R	$T_{vj} = 25\text{ °C}; V_R = V_{RRM}$ $T_{vj} = 180\text{ °C}; V_R = V_{RRM}$	4 mA 100 mA	
V_F	$T_{vj} = 25\text{ °C}; I_F = 14\text{ kA}; \text{max.}$	1,3 V ²⁾	
$V_{(TO)}$ r_T	$T_{vj} = 180\text{ °C}$ $T_{vj} = 180\text{ °C}$	0,7 V 0,04 mΩ	
R_{thjc} R_{thch}	$DSC^{1)}$ $SSC^{1)}$	0,030 °C/W 0,060 °C/W	0,012 °C/W 0,024 °C/W
T_{vj} T_{stg}	$DSC^{1)}$ $SSC^{1)}$	0,005 °C/W 0,010 °C/W	
		- 40 ... + 180 °C - 40 ... + 150 °C	
F	SI units US units	24 ... 30 kN 5400...6750 lbs.	
w		129 g	130 g
Case		E 22	E 35

Features

- Capsule type metal-ceramic packages with precious metal pressure contacts
- Medium voltage, high current rectifier diodes with slim package for lowest thermal resistance. Low power dissipation. Especially suited for water cooling. Forward selections for paralleling available

Typical Applications

- Welding
- Electroplating

¹⁾ DSC = Double sided cooling
SSC = Single sided cooling

²⁾ For parallel connections selected devices are available on request

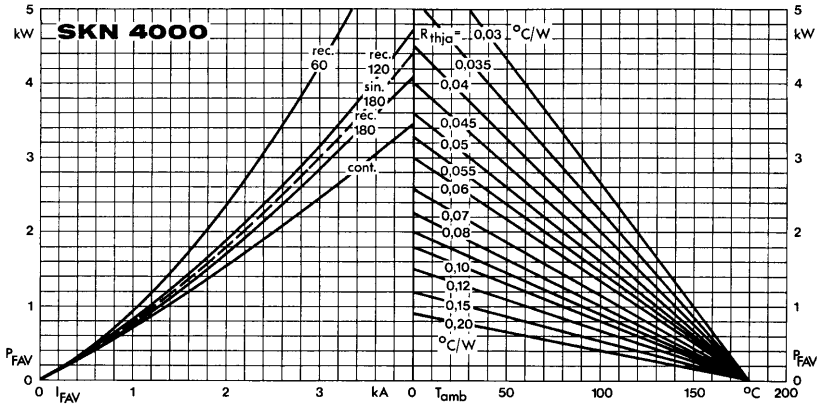


Fig. 2 a Power dissipation vs. forward current and ambient temperature

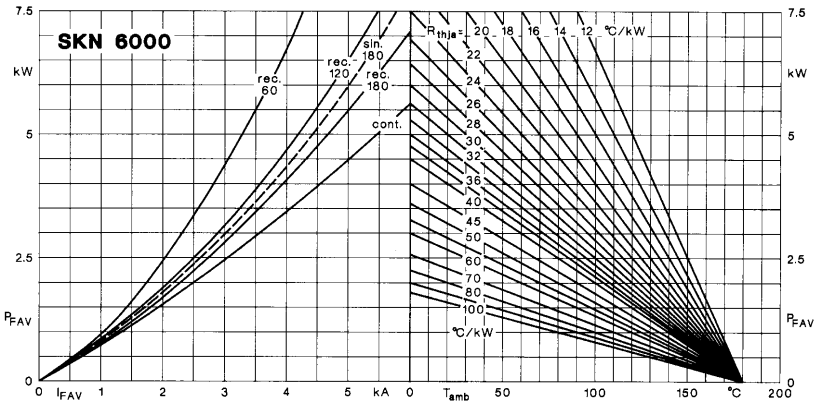


Fig. 2 b Power dissipation vs. forward current and ambient temperature

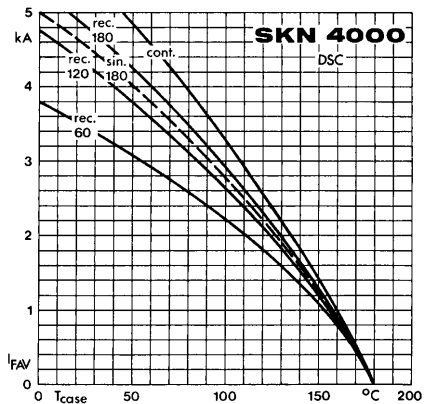


Fig. 3 a Rated forward current vs. case temperature

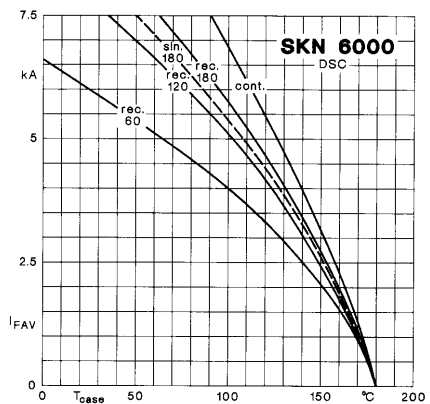


Fig. 3 b Rated forward current vs. case temperature

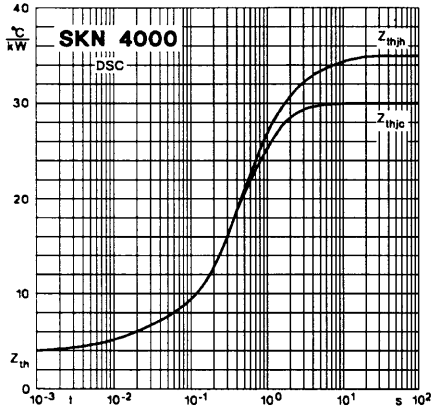


Fig. 5 a Transient thermal impedance vs. time

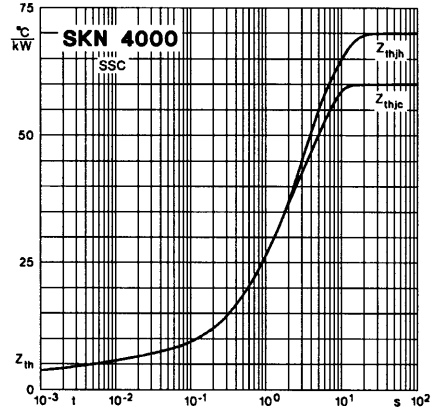


Fig. 5 b Transient thermal impedance vs. time

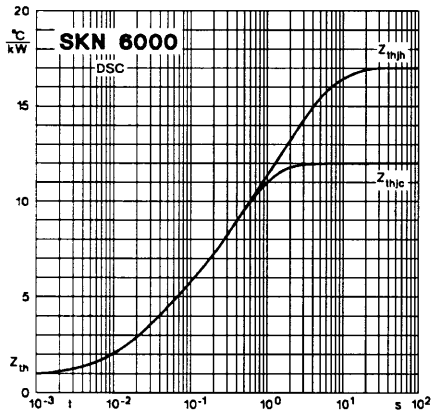


Fig. 5 c Transient thermal impedance vs. time

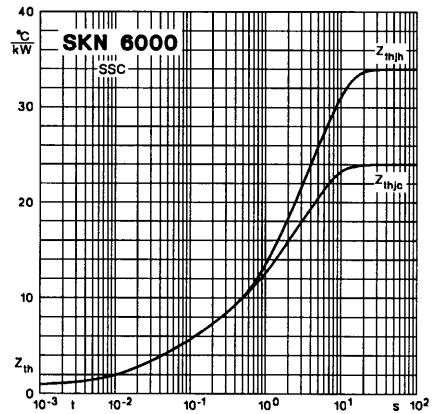


Fig. 5 d Transient thermal impedance vs. time

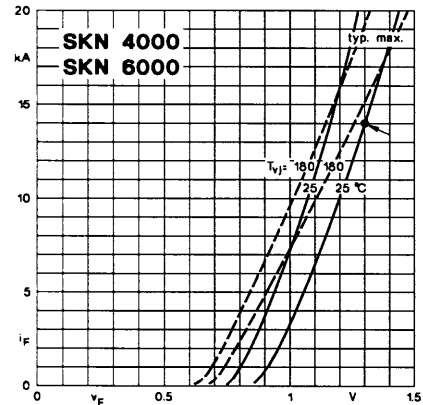


Fig. 6 Forward characteristics

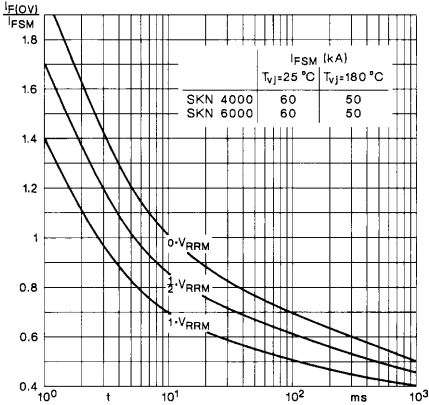


Fig. 7 Surge overload current vs. time

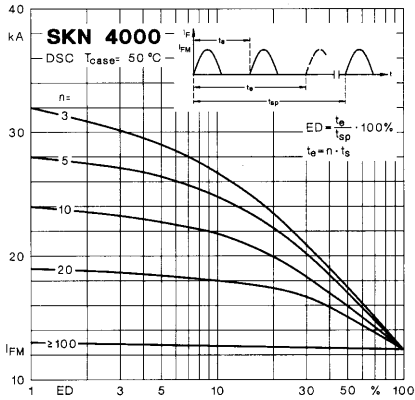


Fig. 12 a Rated peak forward current vs. duty cycle

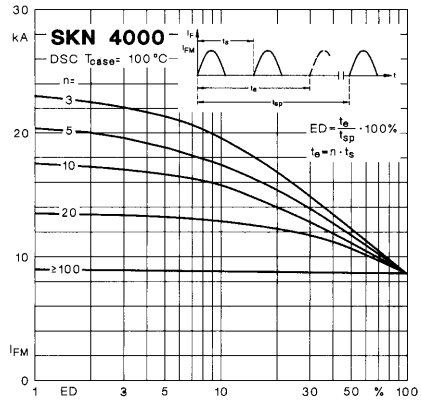


Fig. 12 b Rated peak forward current vs. duty cycle

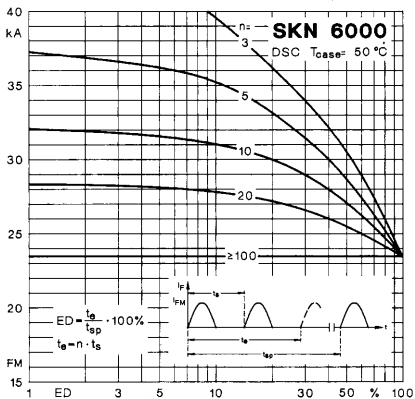


Fig. 12 c Rated peak forward current vs. duty cycle

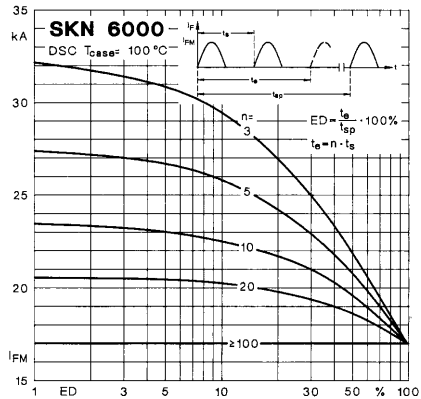


Fig. 12 d Rated peak forward current vs. duty cycle

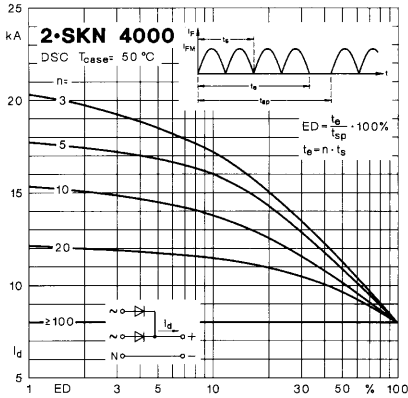


Fig. 13 a Rated direct output current vs. duty cycle

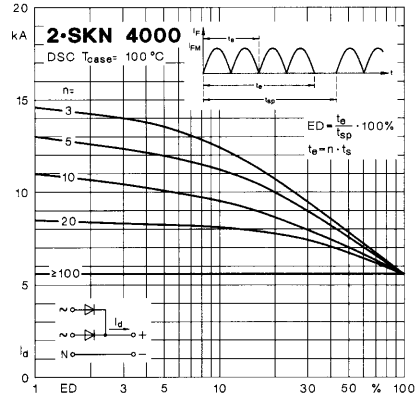


Fig. 13 b Rated direct current vs. duty cycle

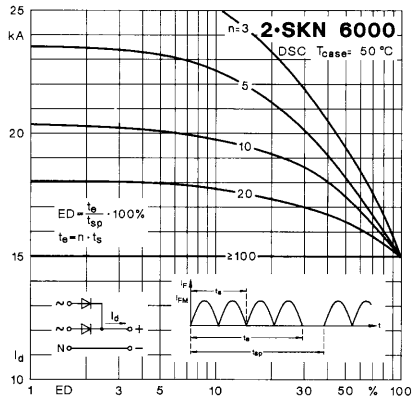


Fig. 13 c Rated direct output current vs. duty cycle

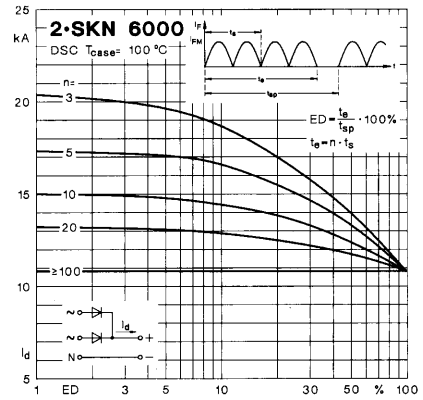
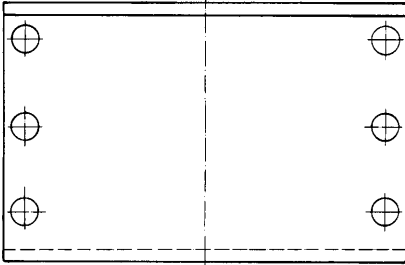
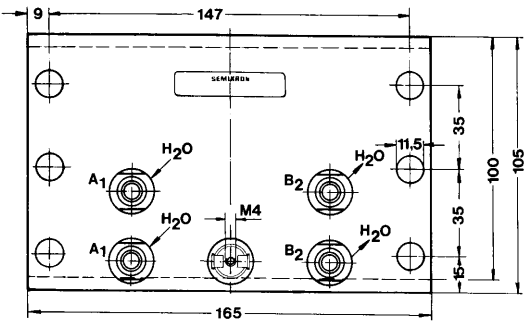
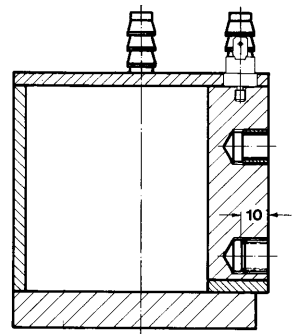
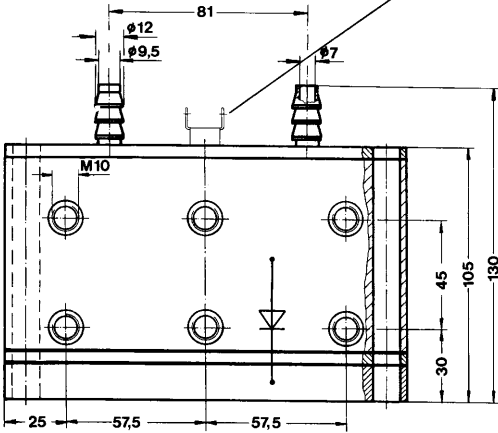


Fig. 13 d Rated direct current vs. duty cycle

SKWD 7000
Case C 4



Bimetal thermal trip
No. 32306700
(T = 50 °C)
max. 250 V 40...60 Hz
max. 10 A
V_{isol} = 2500 V



The contact of the attached bimetal thermal trip opens in case of insufficient water supply or overload. For protection against sudden failure of the cooling water a water flow sensor is recommended. For operation at ED ≤ 50 % this sensor is needed in any case. Due to the large thermal capacitance of the heavy copper busbars a temperature sensor cannot protect the rectifier diode under these conditions.

Dimensions in mm